



## NEW FOR 2011 EXHIBITORS! EASY ON-LINE BOOTH REGISTRATION SYSTEM

Our new *Interactive Exhibit Registration System* and *real-time Exhibit Hall floor plan* allows exhibitors to complete their booth registration on-line. When booth assignments have been made (after November 1, 2010), your exhibit booth location and contact information will be added to an interactive floor plan that will be accessible to potential attendees. You will then be able to add your *Exhibitor Profile*, select your product categories, and take advantage of upgrades.

This new system provides added value for exhibiting companies, including:

- *Company Name*
- *Booth Number*
- *Appointment Manager - Allows attendees to set appointments with exhibitors*
- *Exhibitor Profile*
- *Contact Information*
- *Product Categories - Choose from the comprehensive list of technology specific sub-categories that apply to your business and help exhibit visitors find your company*
- *Personalized Exhibitor Representative Login*

Exhibitors can also choose upgrades that enhance pre-conference marketing activity, including:

- *VISIT US NOW company logo and link*
- *Banner Ads on the Exhibit Floor Plan page with URL link of your choice*
- *Press Releases that can highlight news, products and show specials. Companies participating in the TechCon Sponsorship Program will be entitled to upload unlimited press releases as part of the sponsor benefits.*

### **Benefits for Exhibit Visitors**

Exhibit visitors can use this searchable floor plan to create a list of exhibits to visit and develop a personalized color-coded floor plan by taking advantage of the following features:

- **Multiple Search Criteria** - *Exhibitor Name, Keyword or Product Category*
- **Real-time Alphabetical Listing** of Exhibitors
- **Interactive Floor Plan**
- **Integrated Messaging System** - *Request appointments with exhibitors*
- **Map It** - *Ability to highlight a booth on the floor plan and use color coding to plan time in the Exhibit*
- **Access the SVC Exhibit via the Internet** on your computer or smart phone.
- **Personalized Visitor Login**

### **Professional Development Opportunities, Networking Events and Features that Merge Technology and Business**

The SVC Exhibit in Chicago will be enhanced in 2011 to incorporate new business-friendly events, crafted to provide learning, networking and business opportunities for all TechCon participants throughout the entire two-day Exhibit.

- **A special TechCon Sponsorship Program** offers significant marketing opportunities.
- **Free Wireless Internet** throughout the Exhibit Hall.
- **Special Presentations in the Exhibit Hall** (see page 12 for details)
- *Business Topics Session*
- *Vendor Innovators Showcase*
- *Technical Poster Presentations*
- **Cyber Café** for attendees and exhibitors to use in the Exhibit Hall
- **Reception, lunch, and specialty breaks provided in the Exhibit Hall.**
- **Beer Blast** to create a grand finale to the Exhibit on Wednesday.
- **Lake Cruise Networking Event** on Wednesday evening.

### **Getting Down to Business**

The following changes have been made to the SVC policies for exhibiting in 2011:

- **Booth Assignments will be made after November 1, 2010**—from contracts received with payment on or before this date. After this date, booths will be assigned strictly according to the date that the paid registration is received (see SVC Exhibit Policy on page 18).
- **Set-up** is Monday (8:00 a.m. – 8:00 p.m.) and Tuesday morning (7:00 a.m. – 11:00 a.m.) for the Tuesday and Wednesday Exhibit.



## Sponsorship and Promotional Opportunities at the TechCon

Recognized as THE premier event by engineers, manufacturers, technologists, scientists, and business professionals working in the vacuum coating industry internationally, the SVC TechCon and Exhibit is a wise investment of your conference and marketing dollars.

- **Select one of the TechCon Sponsorships** - see page 17. Sponsors will be widely recognized in all SVC publications and on signage at the TechCon. Non-exhibiting companies are also encouraged to participate in these sponsorships.
- **SVC publishes a 50-word profile for each exhibiting company in the Tech-Con Exhibit Guide (TEG),** which will be mailed to prospective TechCon and Exhibit attendees in early March 2011. **Reserve ad space in the 2011 TEG** as part of your SVC marketing program.
- **Upgrade your on-line profile on the Interactive Exhibit Floor Plan system** by adding a logo and link to your web site, press releases to your company profile page, and a banner ad to the Exhibit Floor Plan page.
- **Participate in the Vendor Innovators Showcase.** These 10-minute presentations are perfect for introducing new products, new equipment, or a new process. Presenters in the Vendor Innovators Showcase do not pay a TechCon presenter registration fee. Go to [www.svc.org](http://www.svc.org) and submit your abstract using the On-line Abstract Submission page (see page 13).

## Questions?

SVC Exhibit Administrator:

Jacque Matanis: 505/897-7743 (direct)  
505/401-8043 (cell)

SVC Administrative Office:

505/856-7188; Fax 505/856-6716

E-mail: [svcinfo@svc.org](mailto:svcinfo@svc.org)

SVC Exhibit Committee Chair:

Cathi Baker: 970/407-6498 (direct)

E-mail: [cathi.baker@aei.com](mailto:cathi.baker@aei.com)

## Reserve Your Exhibit Space Today!

Use the Easy On-line Reservation System featuring a new electronic Exhibitor interface that provides an in-depth Exhibitor profile and product search feature, plus a real-time exhibit layout.

### 2011 SVC Exhibit

Hyatt Regency Chicago on the River Walk, Chicago, Illinois

Tuesday, April 19 • 12:00 p.m. to 6:00 p.m.

Wednesday, April 20 • 10:00 a.m. to 5:00 p.m.

## Nearly 170 manufacturers and suppliers exhibited at TechCon 2010!

4Wave, Inc.	HVA, LLC.	Sigma Technologies International, Inc.
A&N Corporation	Indium Corporation	Soleras Ltd.
AAPS-Advanced Applied Physics Solutions	INFICON	Solvix SA
Advanced Energy Industries, Inc.	Inland Vacuum Industries, Inc.	Sprimag
Advanced Technology & Materials Co., Ltd.	InstruTech, Inc.	Sputtering Components, Inc.
ALCA Technologoy S.r.l.	Intellevation Ltd	Sumitomo (SHI) Cryogenics of America, Inc.
Alcatel Vacuum Products, Inc.	Intlvac	Super Conductor Materials, Inc.
Alicat Scientific, Inc.	InVacuo, Inc.	Superior Technical Ceramics Corp.
Allied Advanced Materials	IonBond LLC	Surface Modification Systems, Inc.
American Institute of Physics (AIP)	J.A. Woollam Co., Inc.	SVC Foundation
Ametek, Inc.	Kashiyama USA, Inc.	Sycon Instruments, Inc.
Angstrom Sciences, Inc.	Kaufman & Robinson, Inc.	Synergy Vacuum, Inc.
Applied Materials	KDF	System Control Technologies (SCT)
ARI Industries, Inc.	Korea Vac-Tec Co., Ltd.	Tecport Optics, Inc.
Arnold Magnetic Technologies	Kurdex Corporation	Tecsun Vacuum Technologoy Engineering Co., Ltd.
Atlas Technologies	Kurt J. Lesker Company	Telemark
Austin Scientific, an Oxford Instruments Company	Leybold Optics USA, Inc.	Temescal
AVT Services Pty Ltd	Lucas/Signatone Corporation	Thermal Conductive Bonding, Inc.
Bekaert Advanced Coatings N.V.	Materials Science, Inc.	Thermionics Vacuum Products
BellowsTech, LLC	MC Power Systems	Thin Film Research Laboratory
Beneq Oy	McVac Manufacturing Co., Inc.	Torr International, Inc.
Bronkhorst USA	MDC Vacuum Products, LLC	TRIBOtechnic
Brooks Automation, Inc.	MEWASA North America, Inc.	Trinos Vacuum Systems, Inc.
Brooks Instrument	Midwest Tungsten Service, Inc.	Tuthill Vacuum & Blower Systems
CeramTec North America	MKS Instruments, Inc.	UC Components, Inc.
Chengdu Ultra Pure Applied Materials Co., Ltd.	Mustang Vacuum Systems, LLC	Ulvac Technologies, Inc.
Coastal Instruments, Inc.	Niles Electronics, Inc.	Umicore Thin Film Products
Coating Materials, A Division of Tico Titanium, Inc.	Nor-Cal Products, Inc.	Vacuum Engineering & Materials Co., Inc.
COMVAT AG	Nu-Tech Precision Metals, Inc.	Vacuum Plus Manufacturing, Inc.
CSM Instruments, Inc.	Odyssey Technical Solutions	Vacuum Process Technology, Inc.
Dark Field Technologies, Inc.	Oerlikon Leybold Vacuum USA Inc.	Vacuum Research Corporation
Darly Custom Technology, Inc.	OmegaVac	Vapor Technologies, Inc.
Denton Vacuum, LLC	OptiLayer, Ltd.	Varian, Inc., Vacuum Technologies
DHF Technical Products	Osaka Vacuum USA, INC.	VAT, Inc.
DON CO.	Pfeiffer Vacuum	Veeco Instruments, Inc.
DynaVac	Physics Today	Vergason Technology, Inc.
EB Sources	PHPK Technologies	VG Scienta, Inc.
EBARA Technologies, Inc.	Phytron, Inc.	VON ARDENNE, Germany
Edwards	Pi Scientific, LLC	W. Theiss Hard-and Software
Evatec	Plasma Process Group	Williams Advanced Materials
Exotech, Inc.	Plasmaterials, Inc.	Yeagle Technology, Inc.
Fil-Tech, Inc.	Plasmionique, Inc.	Zpulser LLC
Filmetrics, Inc.	Polyteknik AS	
FMS USA, Inc.	Precision Plus Vacuum Parts Inc.	
Fraunhofer USA CCL	Process Materials, Inc.	
Gencoqa Ltd.	ProTech Materials	
General Plasma, Inc.	PTB Sales, Inc.	
GENERAL Vacuum Equipment Ltd.	R.D. Mathis Company	
GfE Materials Technology, Inc.	Red Spot Paint & Varnish	
H.C. Starck	Reldan Metals, Co.	
Hauzer Techno Coating BV	Rigaku Vacuum Products	
Heraeus Materials Technology LLC	Rocky Brook Associates, Inc.	
HHV Ltd.	SAGE industrial sales, inc.	
Hine Automation LLC	SCI Engineered Materials, Inc.	
HORIBA Scientific	Semicore Equipment, Inc.	
Huettinger Electronic, Inc.	Seren IPS Inc.	
	Shimadzu Precision Instruments	
	Sidrabe, Inc.	
	Sierra Applied Sciences, Inc.	

The following companies were unable to exhibit at the 2010 TechCon in Orlando due to the volcanic eruption in Iceland on April 15, 2010.

Applied Multilayers Ltd.  
Fraunhofer FEP  
Genefinity S.r.l  
Hartec Innovative Surface Technology  
Impedans Ltd.  
IPT GmbH  
Kolzer  
NAGY Instruments  
PVT Plasma and Vacuum Technologies LLC  
SYSTEC SVS Vacuum Coatings GmbH  
Wieland Dental & Technik GmbH & Co. KG

# SVC Exhibit Application and Contract

Please type or print clearly.

April 19-20, 2011 - Hyatt Regency Chicago on the River Walk, Chicago, IL

**IMPORTANT: Even if you have taken advantage of the Advance Booth Reservation and/or prepaid for your booth, you MUST complete the Interactive On-line Exhibit Application Form at <http://tiny.cc/zvv4y> or submit the form below.**

**Submit Your Application Using the Interactive On-line Exhibit Reservation System with a live floor plan: <http://tiny.cc/zvv4y>**

Exhibiting Company Name (Provide as upper and lower case) \_\_\_\_\_

Exhibit Contact Name \_\_\_\_\_

### Exhibit Contact Mailing Information

Company Name \_\_\_\_\_

(Complete above & below, if different from Exhibiting company)

MS/Building/Street \_\_\_\_\_

City \_\_\_\_\_ State \_\_\_\_\_

Zip \_\_\_\_\_ Country \_\_\_\_\_

Phone \_\_\_\_\_ Fax \_\_\_\_\_

Cell or Alternate Phone \_\_\_\_\_

E-mail \_\_\_\_\_

### Exhibit Company Mailing Information

Web Address \_\_\_\_\_

(Web address to be printed in the TechCon Exhibit Guide & Web Site)

MS/Building/Street \_\_\_\_\_

City \_\_\_\_\_ State \_\_\_\_\_

Zip \_\_\_\_\_ Country \_\_\_\_\_

Phone \_\_\_\_\_ Fax \_\_\_\_\_

Cell or Alternate Phone \_\_\_\_\_

E-mail \_\_\_\_\_

### Complete Items 1-6 in full

1. **Booth Fee:** 10-foot wide booth space (10-foot deep) fee (\$1,750). Number of booths \_\_\_\_\_ x booth fee (\$1,750) \$ \_\_\_\_\_

2. **Advertise in the SVC TechCon Exhibit Guide.**

**Deadline for advertising materials is February 15, 2011.**

The TechCon Exhibit Guide, which includes the 50-word profiles will be mailed in March to an extensive mailing list to promote the TechCon and Exhibit.

<input type="checkbox"/> Covers Full page - circle one: IFC OIFC OBC	Black/White	4 Color	\$ _____
<input type="checkbox"/> Full page - circle one: IBC OIBC	not available	\$2,695	\$ _____
<input type="checkbox"/> Full page	not available	\$2,495	\$ _____
<input type="checkbox"/> Half page	\$1,945	\$2,250	\$ _____
<input type="checkbox"/> Quarter Page	\$1,415	\$1,850	\$ _____
	\$895	\$1,295	\$ _____

3. **Add-ons for the Interactive On-line Exhibit Reservation System and Live Floor Plan** (check boxes below)

**EP-1** Banner Ad on the Exhibit Floor Plan page with URL Link of your choice (\$750) \$ \_\_\_\_\_

Banner will display from September 2010 through July 2011

**EP-2** VISIT US NOW - Link and company Logo with URL Link of your choice (\$475) \$ \_\_\_\_\_

Will you provide a reciprocal link from your Web Site to the SVC Web Site?  Yes  No If yes, we will send an SVC logo and linking information

**EP-3** Press Releases (Product Pages or Show Specials) on Exhibitor's Profile page (Up to 3 Press Releases for \$75) \$ \_\_\_\_\_

All TechCon Sponsors will receive unlimited Press Release postings as part of their Sponsorship Benefits

4. **Promotional Partner with SVC:** Are you willing to distribute electronically designed files created by SVC to your customer database?  Yes  No

5. **Will you be one of our Sponsors?**  Yes  No See opportunities listed on page 17.

If Yes, indicate your choice(s) below and enter the total at the right \$ \_\_\_\_\_

Bronze \$800  Silver \$1,400  Gold \$3,000  Tote Bags \$2,200  Badge Lanyards \$2,200  USB Flash Drive \$3,700

Hotel Reservation Web Splash Page \$675  On-line Registration Web Splash Page \$2,200  Logo Bottled Water \$2,200

Specialty Coffee Station \$2,000  Lake Cruise Networking Event \$1,200  Relaxation Station \$750

E-mail your company logo (high resolution vector file preferred; TIF, EPS or JPEG format) to [svcinfo@svc.org](mailto:svcinfo@svc.org) Total Fee Enclosed \$ \_\_\_\_\_

Payment method:  Check  VISA  MasterCard  Discover  American Express • Card # \_\_\_\_\_

Exp. Date \_\_\_\_\_ 3-digit Security Code \_\_\_\_\_ Signature \_\_\_\_\_ Zip Code \_\_\_\_\_

6. Companies you do NOT wish to be near: (see #4 under Assignment of Booths - page 18) \_\_\_\_\_

### Exhibit Space Location

Booth choices are indicated below. (If purchasing two or three booth spaces, you must choose adjoining spaces—see Exhibit Hall layout)

1 \_\_\_\_\_ 2 \_\_\_\_\_ 3 \_\_\_\_\_ 4 \_\_\_\_\_ 5 \_\_\_\_\_ 6 \_\_\_\_\_ 7 \_\_\_\_\_ 8 \_\_\_\_\_

The undersigned hereby authorizes SVC to reserve exhibit space for use by this company during the 54th SVC Annual Technical Conference and Exhibit and acknowledges receipt of and agrees to abide by the SVC Exhibit Policy and Rules as stated on page 18.

Signature \_\_\_\_\_ Date \_\_\_\_\_

Send registration form and payment to: Society of Vacuum Coaters, 71 Pinon Hill Place NE, Albuquerque, NM 87122-1914 USA • Fax 505/856-6716 • E-mail [svcinfo@svc.org](mailto:svcinfo@svc.org)



## Sponsorship Opportunities at the 2011 TechCon in Chicago

**Become a TechCon Sponsor!** Choose from one of our Level Sponsorships or a special program sponsorship to raise company awareness, promote new products and services and enhance exhibit participation. Official sponsors are recognized during their sponsored event, and also with prominent on-site signage, on the SVC Web Site, in the SVC *Bulletin*, the Preliminary and Final Technical Programs, and TechCon Exhibit Guide.

### Choose the Sponsorship That Fits Your Budget...

#### Gold Sponsor - \$3,000

- Acknowledgement on the SVC Web Site Sponsor page and Logo Link
- Complimentary VISIT US NOW Link and Company Logo (valued at \$475)
- Acknowledgement in the SVC Bulletin, the Preliminary and Final Technical Programs, and TechCon Exhibit Guide
- Acknowledgement on special signage in high traffic areas
- Sponsor of the Wireless Internet – Including the Cyber Café during the Exhibit Open Hours on Tuesday and Wednesday
- Exhibit Reception Sponsor: This Tuesday Afternoon event sponsorship includes special recognition on signage
- Unlimited Press Release Postings on the Exhibitor's Profile page

**For an additional \$500 your company can sponsor the Lake Cruise Networking Event** - (Includes two (2) complimentary tickets to the event. See Lake Cruise Networking Event for details)

#### Silver Sponsor - \$1,400

- Acknowledgement on the SVC Web Site
- Acknowledgement in the SVC Bulletin, the Preliminary and Final Technical Programs, and TechCon Exhibit Guide
- Acknowledgement on SVC TechCon signage
- Break Sponsor for all refreshment breaks
- Refreshments during the Beer Blast – Wednesday afternoon in the Exhibit Hall
- Technology Forum Breakfast Sponsor (Monday and Tuesday morning)
- Heureka! Session Refreshments Sponsor
- Unlimited Press Release Postings on the Exhibitor's Profile page

**For an additional \$500 your company can sponsor the Lake Cruise Networking Event** - (Includes two (2) complimentary tickets to the event. See Lake Cruise Networking Event for details)

#### Bronze Sponsor - \$800

- Acknowledgement on the SVC Web Site
- Acknowledgement in the SVC Bulletin, the Preliminary and Final Technical Programs, and TechCon Exhibit Guide
- Acknowledgement on SVC TechCon signage
- Unlimited Press Release Postings on the Exhibitor's Profile page

**For an additional \$500 your company can sponsor the Lake Cruise Networking Event** - (Includes two (2) complimentary tickets to the event. See Lake Cruise Networking Event for details)

**Unless otherwise indicated, all TechCon Sponsors listed below receive the following Sponsor Benefits:**

- Unlimited Press Release Postings on the Exhibitor's Profile page
- Acknowledgement on the SVC Web Site Sponsor page and Logo Link
- Acknowledgement in the SVC Bulletin, the Preliminary and Final Technical Programs, and TechCon Exhibit Guide
- Acknowledgement on special SVC TechCon Sponsor signage

#### Specialty Coffee Station – \$2,000

Sponsor a specialty coffee station during the Technical Sessions or in the Exhibit Hall. Includes coffee sleeves imprinted with your company logo.

#### Lake Cruise Networking Event – \$1,200

Sponsor the Wednesday Evening Networking Event featuring a buffet dinner and entertainment on a Luxury Cruise Ship. (Includes two (2) complimentary tickets to the event)

#### Relaxation Station – \$750

Sponsor a Massage Chair in the Exhibit Hall on Tuesday and Wednesday.

#### USB Flash Drive – \$3,700

(1 Sponsor) Sponsor the USB Flash Drives that contain the Final Program Abstracts and are given to all Full Conference Registrants.

#### Registration Tote Bags – \$2,200

(4 Sponsors) Tote bags with four (4) company logos on the front and the SVC logo on the reverse will be distributed to all attendees.

#### Badge Lanyards – \$2,200

(1 Sponsor) Badge lanyards containing your logo and the SVC logo will be distributed to all attendees.

#### Hotel Reservation Web Splash Page – \$675

(1 Sponsor) Put your company in front of every attendee who makes their hotel reservation using our On-line Registration system. (December 2010 – April 2011)

#### On-line Registration Web Splash Page – \$2,200

(1 Sponsor) Put your company in front of every attendee who registers for the TechCon using our On-line Registration system. (December 2010 – April 2011)

#### Logo Bottled Water – \$2,200

(1 Sponsor) Bottled water with your logo will be supplied at all breaks during the TechCon.

# SVC EXHIBITOR RULES AND EXHIBIT POLICY

## The Basics

1. The words "Exhibit Management" as used herein refers to the Society of Vacuum Coaters (SVC) and its management contractors. Exhibit space shall be assigned by Exhibit Management in the best interests of the Exhibit as a whole.
2. Exhibitors may not change the booth drape arrangement nor extend their exhibit past the booth side arms into the aisles. Exhibits may not exceed 12 feet in height, and portions above 3 feet in height may not extend more than 4 feet out from the back line of the booth space. Bridges will be allowed in certain locations where they will not obstruct the views of other exhibitors. Please notify SVC if your booth has a Bridge prior to booth assignment. (SVC will review each request prior to booth assignment.)
  - Any portion of the exhibit facing or bordering another exhibitor's booth must have the back portion finished and cannot display identification signs, logos or other materials that would detract from the neighboring exhibitor's booth.
  - Island booths must have adequate line of sight so that the surrounding area can be viewed through the booth and neighboring booths are not obstructed. Booth blocking (walls or drapes that may contribute to obstructed views of neighboring exhibitors) is prohibited.
  - Exhibits may be 12 feet high – depending upon location.
  - Exhibitors who violate these rules will be required to modify their booth on site.
3. The purpose of each exhibit is scientific and educational. Sales during the Exhibit are prohibited.
4. Exhibitors who cancel their booth space on or before December 28, 2010, forfeit 10% of the rental fee. There is no refund for cancellations after December 28, 2010. (If an exhibiting company sends a written request to SVC to cancel their booth registration after December 28, 2010, and if the SVC Exhibit sells out, the exhibiting company will receive a refund of 75% of its booth fee.)
5. An exhibiting company shall not assign, sublet, or apportion the whole or any part of the contracted booth space.
6. Exhibitors may not dismantle the booth before the Exhibit closes without incurring a penalty.
7. Every individual from an exhibiting company must register using the On-line Registration system that will open in mid December, 2010.
  - Personnel who wish to attend all the presentations in the technical sessions and functions that are part of the TechCon program, or who are presenters in the technical sessions, must register for the TechCon as a conference registrant or presenter respectively.
  - Individual exhibit booth persons must register using the same registration system, and may request a Final Program and complimentary daily Exhibitor Pass on-site to attend papers in the technical sessions. AVOID having to stand in line to obtain your Exhibitor badge at On-Site Registration by registering in advance! There is no charge to do this and saves you time and frustration – especially if we have long lines of Exhibit Visitors who also did not register in advance!
8. Only bona fide exhibit personnel are allowed in the Exhibit Hall during set-up.
9. 2011 SVC Exhibitors and Corporate Sponsors may request the mailing list of the TechCon registrants after the TechCon at no charge after they sign the SVC Exhibitor List Rental Agreement.
10. No alcohol may be served in booths by exhibiting companies. Hospitality hosted by individual exhibiting companies for attendees cannot be held in parallel with SVC programs without prior approval.

## SVC Exhibit Point System

The SVC Point System provides exhibiting companies and Corporate Sponsors with a preference in selecting booth locations. Points are accrued based on the number of years each company has exhibited and/or been a Corporate Sponsor, and if exhibit personnel stay in the SVC Headquarters hotel. Points are accumulated as follows:

1. Companies receive one point for each booth rented for each year they have exhibited since 1989. Corporate Sponsors receive one point for each year that they have been a sponsor.
2. If Company A has 'x' points and is purchased by Company B, which has 'y' points, then Company B will have either 'x' or 'y' points, whichever is the greater amount. SVC must be notified in writing of the purchase prior to November 1 of the year before the TechCon.

3. Exhibiting companies who reserve sleeping rooms for all of their personnel in the Hyatt Regency on the River Walk, Chicago, prior to February 16, 2011 will receive THREE additional points towards future booth location preference. Exhibiting companies who have the majority of their personnel registered in the Hyatt Regency, but have not done so on or before February 16, 2011 will receive ONE additional point. There are great advantages to exhibitors who stay in this property from a networking perspective. In addition, your support for SVC's commitment to the hotel is very important to the success of the annual TechCon and Exhibit.

## Assignment of Booths

1. Booth assignments will begin after **November 1, 2010** from contracts received with payment by that time. Each company will be asked to provide eight (8) choices for their booth location. Based on the points a company has accumulated, each company will be given their booth choice, as available.
2. Companies requesting Islands – four (4) contiguous booths – will be assigned FIRST. The point system will still apply to all companies within this group.
3. In the case of two companies having the same number of points, the earliest paid booth registration date will be given preference.
4. After November 1, 2010 booths will be assigned strictly according to the date that the paid registration is received (payment by credit card is acceptable). If a company's booth choices have already been assigned, the next best booth location will be given to the company.
5. Exhibiting companies that do NOT wish to be located near probable exhibitors, must provide a COMPLETE list with their Exhibit Application and Contract. If a later request is received, Exhibit Management will make every effort to accommodate the request, but this cannot be guaranteed.
6. Companies that are legally related entities can request to be located next to each other. The request must be made in writing. Exhibit Management will make every effort to accommodate the request.
7. Exhibit space shall be assigned by Exhibit Management in the best interests of the Exhibit as a whole. Exhibitors must agree to accept relocation if it becomes necessary or advisable in the sole judgment of Exhibit Management.
8. Exhibit Management reserves the right to change the published floor plan – i.e., "end" booths are not guaranteed. After final assignment, space location may not be changed.

## Additional Rules

1. Exhibitor agrees to indemnify and hold harmless SVC, the hotel or other facility housing the Exhibit, and their respective agents, servants, and employees from any loss, damage, liability, costs, attorney's fees, or other of whatsoever nature arising from exhibitor's participation in the event, including but not limited to claims due to the injury, damage or loss to exhibitor's displays, equipment and other property brought upon the premises of the exhibit facility, except for claims solely resulting from the gross negligence of Exhibit Management and/or the hotel/exhibit facility. The exhibitor understands that neither SVC nor the hotel/exhibit facility maintains insurance covering the exhibitor's property, and it is the sole responsibility of the exhibitor to obtain such insurance.
2. Exhibitor agrees to obtain Commercial General Liability and Property insurance to be in effect during the dates of the event, including move-in and move-out days, and will furnish a certificate of insurance to SVC. Said limits of insurance will be in an amount not less than \$1 million per occurrence and \$2 million in the aggregate. Exhibitor's insurance will list SVC Exhibit Management and the Hyatt Regency on the River Walk, Chicago, as additional co-insureds for the period of the Exhibit, including move-in and move-out periods. Exhibitor agrees to waive the right of subrogation by their insurance carriers to recover loss sustained under the respective insurance contracts for real and personal property.
3. Exhibitor agrees to abide by all SVC's rules and regulations, including but not limited to, its Code of Ethics and to conduct itself and its business with fairness and honesty, loyalty to its associates, employees, clients, customers and employees, and fidelity to the needs of the public. SVC reserves the right to deny participation in its programs and activities to individuals and organizations that violate its rules or whose participation, in SVC's sole discretion, is deemed detrimental to the interests and purposes of SVC.



## 2011 SVC TechCon Education Program

April 16-21, 2011 • Hyatt Regency Chicago on the River Walk, Chicago, IL

### **Preliminary Course Roster**

#### **Saturday, April 16**

Vacuum Systems, Materials and Operation (O'Hanlon) V-204  
An Introduction to Physical Vapor Deposition (PVD) Processes (Shah) C-103  
Practical Aspects of Optical Coatings (Morton) C-302  
Thin Film Growth and Microstructure Evolution (Greene) C-311

#### **Sunday, April 17**

Sputter Deposition (Greene) - Day 1 of 2-Day Tutorial C-203 (Sunday and Monday)  
Optical Coating Design and Monitoring (Willey) C-301  
Plasma Modification of Polymer Materials and Plasma Web Treatment (Grace) C-314  
High Power Impulse Magnetron Sputtering (Ehassarian & Anders) C-323  
**New!** Introduction to Photovoltaic Materials and Photovoltaics (Martin) C-327

#### **Monday, April 18**

Sputter Deposition onto Flexible Substrates (McClure) C-211  
Numerical Methods for Optical Coatings (Dobrowolski) C-303  
Characterization of Thin Films (Christensen) C-322

#### **Tuesday, April 19**

Practical Aspects of Vacuum Technology: Operation and Maintenance of  
Production Vacuum Systems (Langley) V-207  
Introduction to Plasma Processing Technology (Baránková & Bárdos) C-210 (Half Day PM)  
Reactive Sputter Deposition (Greene) C-315  
Properties and Applications of Tribological Coatings (Matthews) C-328 (Half Day AM)

#### **Wednesday, April 20**

Sputter Deposition in Manufacturing (Glocker) C-208  
Troubleshooting for Thin Film Deposition Processes (Ash) C-212  
ITO and Other Transparent Conductive Coatings: Fundamentals, Deposition,  
Properties, and Applications (Bright) C-304  
**New!** Nanostructures: Strategies for Self-Organized Growth (Greene) C-318 (Half Day AM)  
**New!** Industrial Ion Sources (Zhurin) C-329 (Half Day PM)

#### **Thursday, April 21**

Diamond Like Carbon Coatings – from Basics to Industrial Realization (Schuelke,  
Van de Kolk, and Bewilogua) C-320 (Half Day AM)  
Alternative Transparent Conductive Oxides (TCOs) to ITO (Bright) C-321 (Half Day AM)  
Atmospheric Plasma Technologies (Baránková & Bárdos) C-324 (Half Day AM)  
Manufacture of Precision Evaporative Coatings (Oliver) C-326 (Half Day AM)

### **Register for Tutorials at the 2011 TechCon in Chicago when you register for the conference.**

**On-line registration opens in mid-December 2010.**

You do not have to register for the TechCon or be a member of SVC to attend the Tutorial Courses. Visit the SVC Web Site for Tutorial Course descriptions, topical outline, detailed syllabus and biographical sketch of each instructor.

**Students:** Take advantage of our discounted fees for full-time students. You must have a valid student identification to qualify for these special rates.

## **International Outreach Program**

### **SVC Offers Tutorial Courses in Germany and China in 2010**

As part of the SVC Strategic Plan that includes ongoing development and expansion of an International Outreach Program, the Society is offering Tutorial Courses in Germany and China.

#### **SVC C-317**

***The Practice of Reactive Sputtering***  
Instructor: Allan Matthews, University of Sheffield, UK

This Tutorial Course will be offered on September 16, 2010 at PSE 2010 - Twelfth International Conference on Plasma Surface Engineering Conference and Exhibition September 13–17, 2010  
Kongresshaus, Garmisch-Partenkirchen (Germany)

For more information, visit <http://www.svc.org/Education/PSE-2010-Germany-September-2010.cfm>



#### **SVC V-204**

### ***Vacuum Systems, Materials and Operation***

Instructor: John F. O'Hanlon, Professor Emeritus of Electrical and Computer Engineering, University of Arizona

This Tutorial Course will be offered on October 18 and 19, 2010 and hosted for international attendees by the Flex Company Limited, located in Beijing, China.

For more information on this Tutorial Course, visit <http://www.svc.org/Education/Beijing-China-October-2010.cfm>

# TECHCON 2011 » EXHIBIT HALL LAYOUT

Submit Your Application Using the Interactive On-line Exhibit Reservation System with a live floor plan: <http://tiny.cc/zvv4y>

## 2011 SVC Exhibit

Hyatt Regency Chicago on the River Walk, Chicago, Illinois

Tuesday, April 19 • 12:00 p.m. to 6:00 p.m.

Wednesday, April 20 • 10:00 a.m. to 5:00 p.m.

### Booth Set-up Hours

Monday, April 18 8:00 a.m. – 8:00 p.m.

Tuesday, April 19 7:00 a.m. – 11:00 a.m.

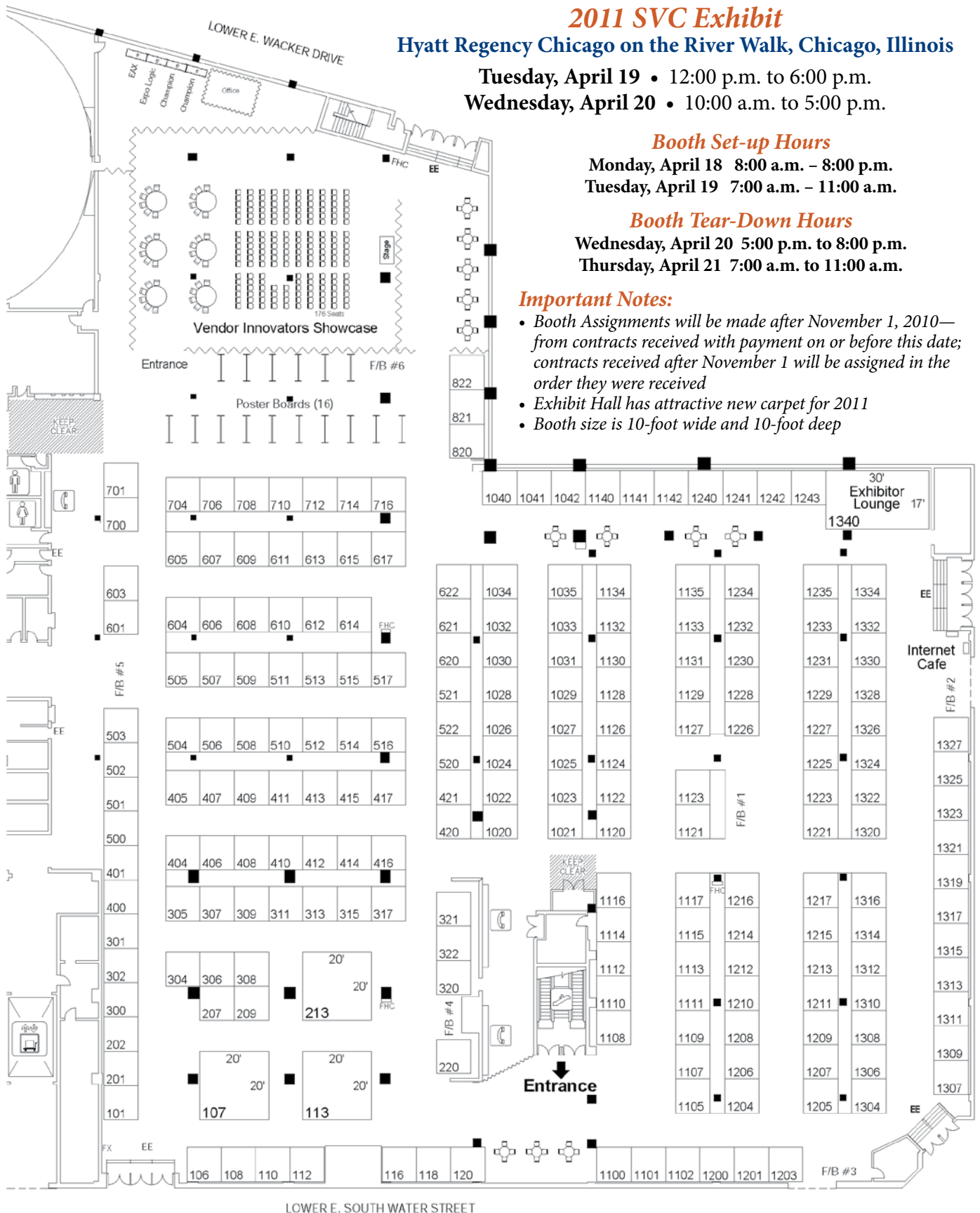
### Booth Tear-Down Hours

Wednesday, April 20 5:00 p.m. to 8:00 p.m.

Thursday, April 21 7:00 a.m. to 11:00 a.m.

### Important Notes:

- Booth Assignments will be made after November 1, 2010—from contracts received with payment on or before this date; contracts received after November 1 will be assigned in the order they were received
- Exhibit Hall has attractive new carpet for 2011
- Booth size is 10-foot wide and 10-foot deep



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